

## Features

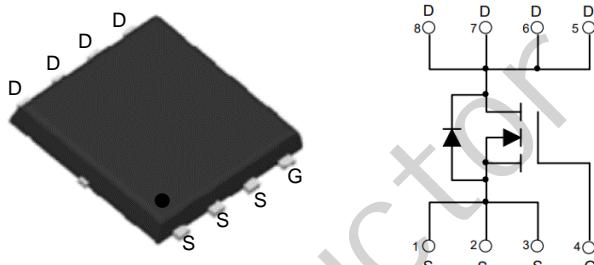
- High density cell design for ultra low  $R_{DS(ON)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

## Product Summary

$V_{DS}$	$R_{DS(ON)} \text{ MAX}$	$I_D \text{ MAX}$
60V	17mΩ@10V	50A
	23mΩ@4.5V	

## Application

- Power switching application



PDFN5X6-8L top view

Schematic diagram

## Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Symbol	Parameter	Rating	Unit
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## Common Ratings (TC=25°C Unless Otherwise Noted)

$V_{DS}$	Drain-Source Breakdown Voltage	60	V
$V_{GS}$	Gate-Source Voltage	±20	V
$T_J$	Maximum Junction Temperature	150	°C
$T_{STG}$	Storage Temperature Range	-50 to 155	°C
$I_S$	Diode Continuous Forward Current	50	A

## Mounted on Large Heat Sink

$I_{DM}$	Pulse Drain Current Tested	$T_c=25^\circ\text{C}$	190	A
$I_D$	Continuous Drain Current@GS=10V	$T_c=25^\circ\text{C}$	50	A
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	83	W
$E_{AS}$	Single pulse avalanche energy <sup>Note1</sup>		98	mJ

Electrical Characteristics (T <sub>J</sub> =25°C unless otherwise noted)						
Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
B <sub>V(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.1	1.6	2.5	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	--	13	17	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	--	18	23	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz	--	1890	--	pF
C <sub>OSS</sub>	Output Capacitance		--	115	--	pF
C <sub>RSS</sub>	Reverse Transfer Capacitance		--	90	--	pF
<b>Switching Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	--	40	--	nC
Q <sub>gs</sub>	Gate Source Charge		--	7	--	nC
Q <sub>gd</sub>	Gate Drain Charge		--	8.5	--	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30V, R <sub>L</sub> =6.7Ω, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	--	13	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	25	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	60	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	10	--	nS
<b>Source- Drain Diode Characteristics</b>						
V <sub>SD</sub>	Forward on voltage	T <sub>J</sub> =25°C, I <sub>S</sub> =20A,	--	0.8	1.2	V

Note: 1.L=0.5mH, VDD=30V, Start T<sub>J</sub>=25°C.

### Typical Operating Characteristics

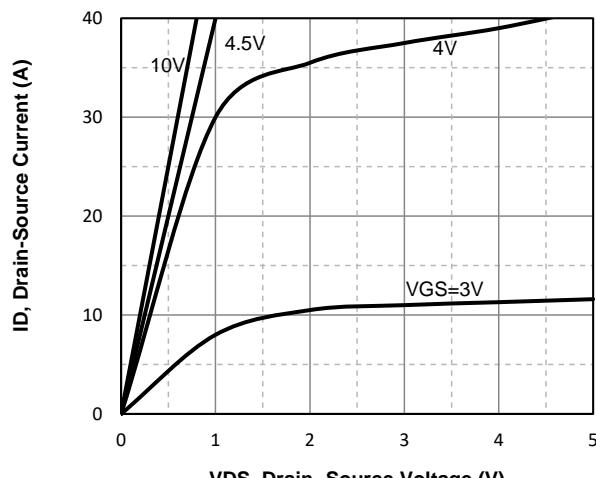


Fig1. Typical Output Characteristics

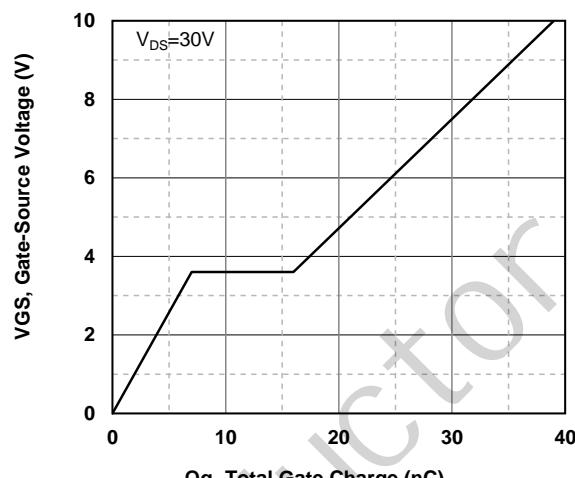


Fig2. Typical Gate Charge Vs. Gate-Source Voltage

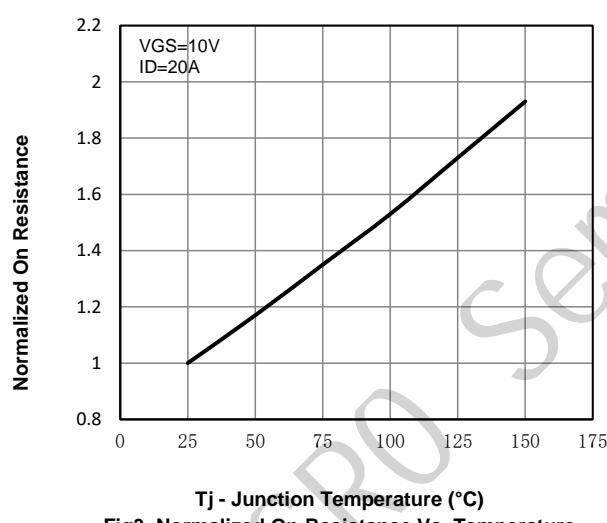


Fig3. Normalized On-Resistance Vs. Temperature

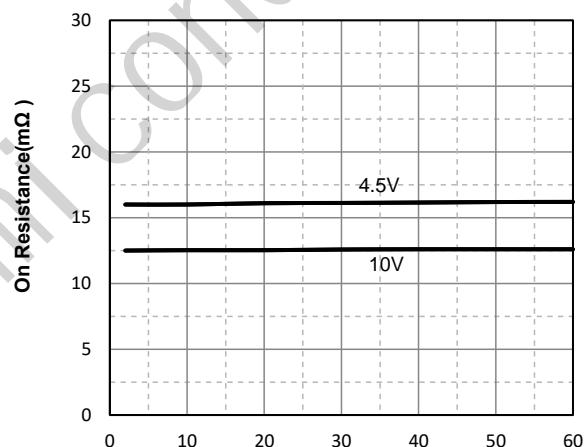


Fig4. On-Resistance Vs. Drain-Source Current

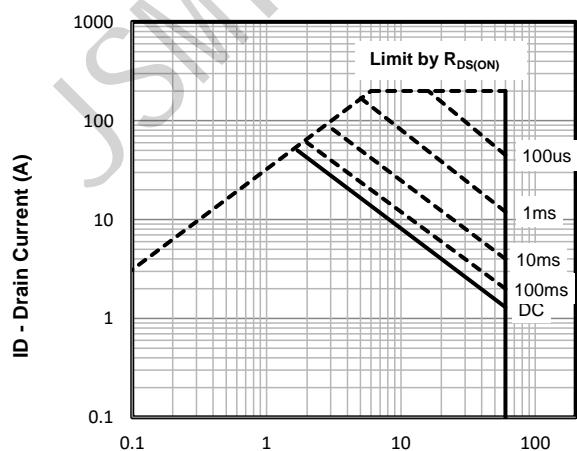


Fig5. Maximum Safe Operating Area

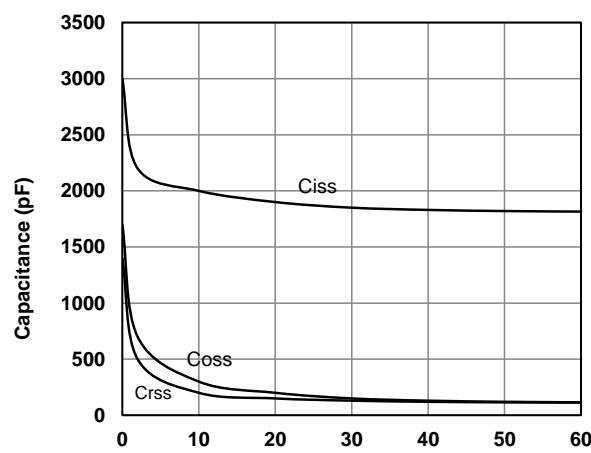


Fig6. Typical Capacitance Vs. Drain-Source Voltage

**PDFN5X6-8L Package information**